

METHOD OF ADJUSTING TEMPERATURE OF SUBSTRATE SUPPORT AND INSPECTION APPARATUS

ABSTRACT

A method of adjusting a substrate support temperature when inspecting devices on a substrate, wherein the substrate support includes a wafer placement surface and temperature sensors, and a temperature adjuster adjusting a wafer placement surface temperature is shared among the devices, and wherein the method includes: upon switching an inspection target device, (A) calculating a first operation amount based on a temperature measured by a preceding temperature sensor corresponding to a device which was an inspection target, and a target temperature; (B) calculating a second operation amount based on a temperature measured by a next temperature sensor corresponding to a device to be a next inspection target, and a target temperature; (C) calculating an operation amount of the temperature adjuster upon the switching by adding values from multiplying a variable α by the first operation amount and multiplying $1-\alpha$ by the second operation amount; and (D) outputting the operation amount.

(Fig. 5)